DDR3 Code Information

Component

Part Number Decoder

SAMSUNG

SAMSUNG ELECTRONICS

K 4 B X X X X X X - X X X X X X X
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. DRAM : 4

3. Small Classification
 B : DDR3 SDRAM

4~5. Density
 51 : 512Mb
 1G : 1G
 2G : 2G
 4G : 4G

6~7. Bit Organization
 04 : x4
 08 : x8
 16 : x16

8. # of Internal Banks
 3 : 4 Banks
 4 : 8 Banks
 5 : 16 Banks

9. Interface, VDD, VDDQ
 6 : SSTL, 1.5V, 1.5V

10. Generation
 M : M-die
 A : A-die
 B : B-die
 C : C-die
 D : D-die
 E : E-die
 F : F-die
 G : G-die
 H : H-die

11. "—"

12. Package
 Z : FBGA (Lead-Free)
 H : FBGA (Lead-Free & Halogen-Free)
 J : FBGA (Lead-Free, DDP)
 M : FBGA (Lead-Free & Halogen-Free, DDP)
 B : FBGA (Lead-Free & Halogen-Free, Flip Chip)

13. Temp, Power
 C : Commercial Temp.(0°C ~ 85°C), Normal Power
 Y : Commercial Temp.(0°C ~ 85°C), Low VDD(1.35V)

14~15. Speed (Wafer/Chip Biz/BGD: 00)
 F7 : DDR3-800 (400Mhz@CL=6, tRCD=6, tRP=6)
 F8 : DDR3-1066 (533MHz@CL=7, tRCD=7, tRP=7)
 H9 : DDR3-1333 (667MHz@CL=9, tRCD=9, tRP=9)
 K0 : DDR3-1600 (800MHz@CL=11, tRCD=11, tRP=11)
 MA : DDR3-1866 (933MHz@CL=13, tRCD=13, tRP=13)

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16. Packing "Packing Type Reference"

- Common to all products, except of Mask ROM

- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"

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